

1. Record Nr.	UNINA9910823317103321
Autore	Gilman John J (John Joseph)
Titolo	Chemistry and physics of mechanical hardness [[electronic resource] /] / John J. Gilman
Pubbl/distr/stampa	Hoboken, NJ : Wiley, c2009
ISBN	1-282-18824-0 9786612188244 0-470-44683-8 0-470-44682-X
Descrizione fisica	1 online resource (229 p.)
Collana	Wiley series on processing of engineering materials
Classificazione	CHE 380f PHY 202f UQ 8025 WER 720f
Disciplina	620.1/126 620.1126
Soggetti	Hardness Strength of materials
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	"A Wiley-Interscience publication."
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	CHEMISTRY AND PHYSICS OF MECHANICAL HARDNESS; TABLE OF CONTENTS; Preface; 1 Introduction; 1.1 Why Hardness Matters (A Short History); 1.2 Purpose of This Book; 1.3 The Nature of Hardness; References; 2 Indentation; 2.1 Introduction; 2.2 The Chin-Gilman Parameter; 2.3 What Does Indentation Hardness Measure?; 2.4 Indentation Size Effect; 2.5 Indentation Size (From Macro to Nano); 2.6 Indentation vs. Scratch Hardness; 2.7 Blunt or Soft Indenters; 2.8 Anisotropy; 2.9 Indenter and Specimen Surfaces; References; 3 Chemical Bonding; 3.1 Forms of Bonding; 3.2 Atoms; 3.3 State Symmetries 3.4 Molecular Bonding (Hydrogen) 3.5 Covalent Bonds; 3.6 Bonding in Solids; 3.6.1 Ionic Bonding; 3.6.2 Metallic Bonding; 3.6.3 Covalent Crystals; 3.7 Electrodynamic Bonding; 3.8 Polarizability; References; 4 Plastic Deformation; 4.1 Introduction; 4.2 Dislocation Movement; 4.3 Importance of Symmetry; 4.4 Local Inelastic Shearing of Atoms; 4.5

Dislocation Multiplication; 4.6 Individual Dislocation Velocities (Microscopic Distances); 4.7 Viscous Drag; 4.7.1 Pure Metals; 4.7.2 Covalent Crystals; 4.8 Deformation-Softening and Elastic Relaxation; 4.9 Macroscopic Plastic Deformation; References  
5 Covalent Semiconductors 5.1 Introduction; 5.2 Octahedral Shear Stiffness; 5.3 Chemical Bonds and Dislocation Mobility; 5.4 Behavior of Kinks; 5.5 Effect of Polarity; 5.6 Photoplasticity; 5.7 Surface Environments; 5.8 Effect of Temperature; 5.9 Doping Effects; References; 6 Simple Metals and Alloys; 6.1 Intrinsic Behavior; 6.2 Extrinsic Sources of Plastic Resistance; 6.2.1 Deformation-Hardening; 6.2.2 Impurity Atoms (Alloying); 6.2.3 Precipitates (Clusters, Needles, and Platelets); 6.2.4 Grain-Boundaries; 6.2.5 Surface Films (Such as Oxides); 6.2.6 Magnetic Domain Walls  
6.2.7 Ferroelectric Domain-Walls 6.2.8 Twin Boundaries; References; 7 Transition Metals; 7.1 Introduction; 7.2 Rare Earth Metals; References; 8 Intermetallic Compounds; 8.1 Introduction; 8.2 Crystal Structures; 8.2.1 Sigma Phase; 8.2.2 Laves Phases; 8.2.3 Ni<sub>3</sub>Al; 8.3 Calculated Hardness of NiAl; 8.4 Superconducting Intermetallic Compounds; 8.5 Transition Metal Compounds; References; 9 Ionic Crystals; 9.1 Alkali Halides; 9.2 Glide in the NaCl Structure; 9.3 Alkali Halide Alloys; 9.4 Glide in CsCl Structure; 9.5 Effect of Impurities; 9.6 Alkaline Earth Fluorides; 9.7 Alkaline Earth Sulfides  
9.8 Photomechanical Effects 9.9 Effects of Applied Electric Fields; 9.10 Magneto-Plasticity; References; 10 Metal-Metalloids (Hard Metals); 10.1 Introduction; 10.2 Carbides; 10.3 Tungsten Carbide; 10.4 Borides; 10.5 Titanium Diboride; 10.6 Rare Metal Diborides; 10.7 Hexaborides; 10.8 Boron Carbide (Carbon Quasi-Hexaboride); 10.9 Nitrides; References; 11 Oxides; 11.1 Introduction; 11.2 Silicates; 11.2.1 Quartz; 11.2.2 Hydrolytic Catalysis; 11.2.3 Talc; 11.3 Cubic Oxides; 11.3.1 Alkaline Earth Oxides; 11.3.2 Perovskites; 11.3.3 Garnets; 11.3.3.1 (Y<sub>3</sub>Al<sub>5</sub>O<sub>12</sub>)-YAG  
11.4 Hexagonal (Rhombohedral) Oxides

---

#### Sommario/riassunto

A comprehensive treatment of the chemistry and physics of mechanical hardness Chemistry and Physics of Mechanical Hardness presents a general introduction to hardness measurement and the connections between hardness and fundamental materials properties. Beginning with an introduction on the importance of hardness in the development of technology, the book systematically covers: Indentation Chemical bonding Plastic deformation Covalent semiconductors Simple metals and alloys Transition metals Intermetallic compounds Ionic crystals

---